

## ZVN2110GTC-VB Datasheet N-Channel 100-V (D-S) MOSFET

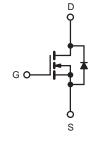
| PRODUCT SUMMARY     |                                 |                    |  |  |
|---------------------|---------------------------------|--------------------|--|--|
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)         | I <sub>D</sub> (A) |  |  |
| 100                 | 0.100 at V <sub>GS</sub> = 10 V | 5.0                |  |  |
|                     | 0.120 at $V_{GS}$ = 4.5 V       | 4.5                |  |  |

#### FEATURES

- Halogen-free According to IEC 61249-2-21
  Definition
- Trench Power MOSFETs
- 175 °C Maximum Junction Temperature
- Compliant to RoHS Directive 2002/95/EC







N-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b>                                 | S T <sub>A</sub> = 25 °C, unles | ss otherwise r                    | noted |              |      |
|---|---------------------------------|-----------------------------------|-------|--------------|------|
| Parameter   |                                 | Symbol                            | 10 s  | Steady State | Unit |
| Drain-Source Voltage  |                                 | V <sub>DS</sub>                   | 100   |              | V    |
| Gate-Source Voltage   |                                 | V <sub>GS</sub>                   | ± 20  |              | v    |
| Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>a</sup> | T <sub>A</sub> = 25 °C          | I <sub>D</sub>                    | 5.0   | 4.5          |      |
|   | T <sub>A</sub> = 70 °C          |                                   | 3.5   | 3.0          | А    |
| Pulsed Drain Current  |                                 | I <sub>DM</sub>                   | 25    |              | A    |
| Avalanche Current   |                                 | I <sub>AS</sub>                   | 15    |              |      |
| Single Pulse Avalanche Energy                                   |                                 | E <sub>AS</sub>                   | 11    |              | mJ   |
| Movimum Dower Dissinctiona                                      | T <sub>A</sub> = 25 °C          | P <sub>D</sub>                    | 3.3   | 1.7          | W    |
| Maximum Power Dissipation <sup>a</sup>                          | T <sub>A</sub> = 70 °C          | ۰D                                | 2.3   | 1.2          |      |
| Operating Junction and Storage Temperature Range                |                                 | T <sub>J</sub> , T <sub>stq</sub> | - 55  | to 175       | °C   |

| THERMAL RESISTANCE RATINGS               |              |                   |         |         |      |
|--|--------------|-------------------|---------|---------|------|
| Parameter                                |              | Symbol            | Typical | Maximum | Unit |
| Mauinum hursting to Archingt a           | t ≤ 10 s     | R <sub>thJA</sub> | 36      | 45      |      |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State |                   | 75      | 90      | °C/W |
| Maximum Junction-to-Foot (Drain)         | Steady State | R <sub>thJF</sub> | 17      | 20      |      |

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

| <b>SPECIFICATIONS</b> $T_J = 25 \text{ °C}$ , unless otherwise noted |   |  |      |       |       |      |  |
|--|---|--|------|-------|-------|------|--|
| Parameter  | Symbol  | Test Conditions  | Min. | Тур.  | Max.  | Unit |  |
| Static   |   |  | •    | •     | •     |      |  |
| Drain-Source Breakdown Voltage V <sub>DS</sub>                       |   | V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA   |      |       |       | V    |  |
| Gate Threshold Voltage   | V <sub>GS(th)</sub>   | $V_{DS} = V_{GS}, I_D = 250 \ \mu A$   | 1.5  |       | 3     | v    |  |
| Gate-Body Leakage  | I <sub>GSS</sub>  | $V_{DS} = 0 V, V_{GS} = \pm 20 V$  |      |       | ± 100 | nA   |  |
| Zero Gate Voltage Drain Current                                      | laaa  | V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V   |      |       | 1     | μΑ   |  |
|  | I <sub>DSS</sub>  | $V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$                        |      |       | 20    |      |  |
| On-State Drain Current <sup>a</sup>                                  | I <sub>D(on)</sub>  | $V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$                                      | 40   |       |       | А    |  |
| Drain-Source On-State Resistance <sup>a</sup>                        |   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.0 A   |      | 0.110 |       |      |  |
|  | R <sub>DS(on)</sub>   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.0 A, T <sub>J</sub> = 125 °C                      |      | 0.122 |       | Ω    |  |
|  |   | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.0 A, T <sub>J</sub> = 175 °C                      |      | 0.140 |       |      |  |
|  |   | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.1 A  |      | 0.120 |       |      |  |
| Forward Transconductance <sup>a</sup>                                | 9 <sub>fs</sub>   | V <sub>DS</sub> = 15 V, I <sub>D</sub> = 4.0 A   |      | 25    |       | S    |  |
| Diode Forward Voltage <sup>a</sup>                                   | V <sub>SD</sub>   | I <sub>S</sub> = 1.7 A, V <sub>GS</sub> = 0 V  |      | 0.8   | 1.2   | V    |  |
| Dynamic <sup>b</sup>   | •   |  | •    | •     | •     |      |  |
| Total Gate Charge  | Qg  |  |      | 18    | 27    |      |  |
| Gate-Source Charge   | $Q_{gs}$ V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4.0 A |  | 3.4  |       | nC    |      |  |
| Gate-Drain Charge  | Q <sub>gd</sub>   |  |      | 5.3   |       | 1    |  |
| Gate Resistance  | Rg  | V <sub>GS</sub> = 0.1 V, f = 5 MHz   | 0.5  | 1.4   | 2.4   | Ω    |  |
| Turn-On Delay Time   | t <sub>d(on)</sub>  |  |      | 10    | 20    |      |  |
| Rise Time  | t <sub>r</sub>  | $V_{DD}$ = 50 V, $R_L$ = 30 $\Omega$   |      | 10    | 20    |      |  |
| Turn-Off Delay Time  | t <sub>d(off)</sub>   | $\text{I}_\text{D}\cong$ 1 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 6 $\Omega$ |      | 25    | 50    | ns   |  |
| Fall Time  | t <sub>f</sub>  |  |      | 12    | 24    |      |  |
| Source-Drain Reverse Recovery Time                                   | t <sub>rr</sub>   | I <sub>F</sub> = 1.7 A, dI/dt = 100 A/µs   |      | 50    | 80    |      |  |

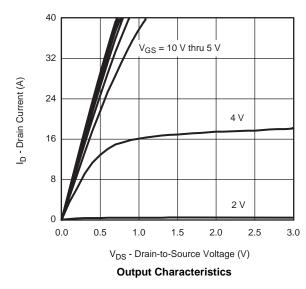
Notes:

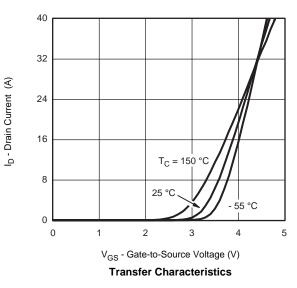
a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

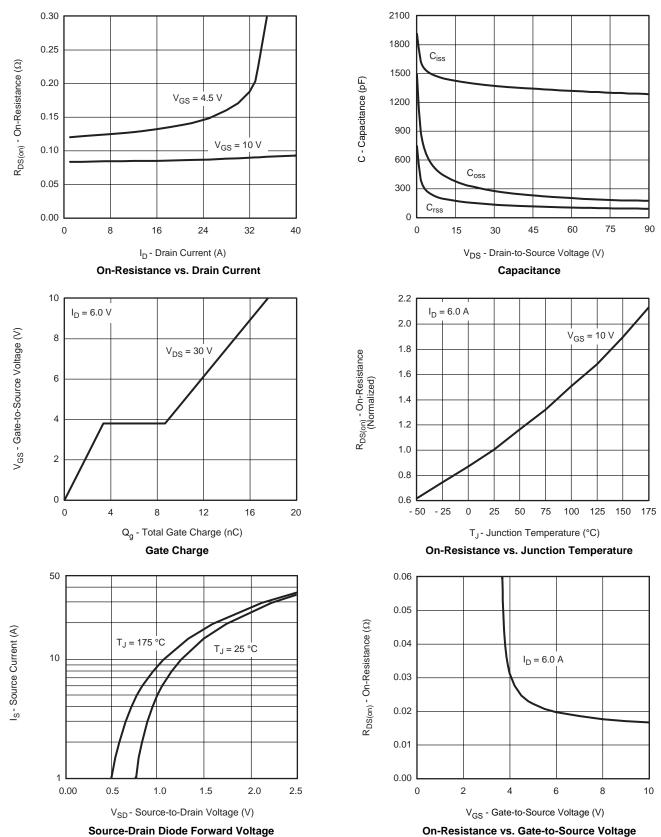




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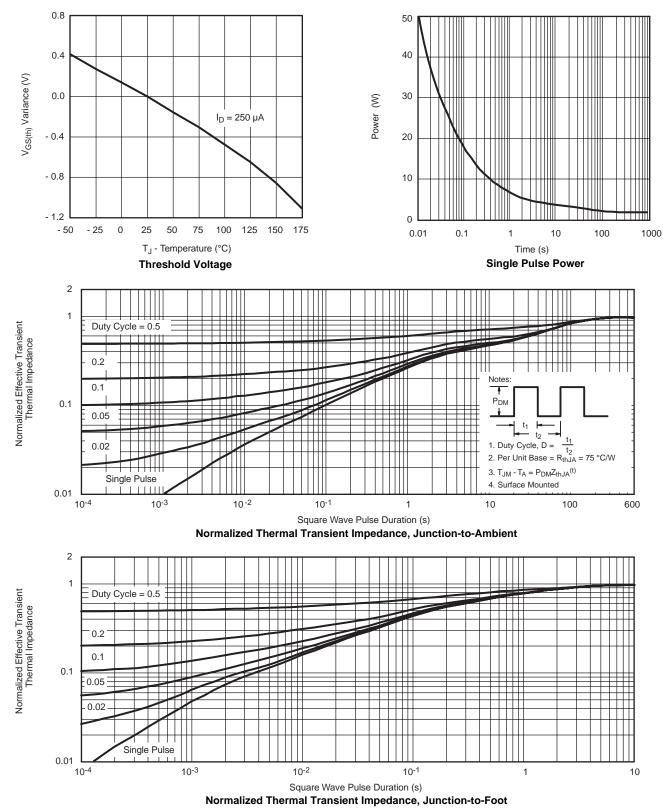


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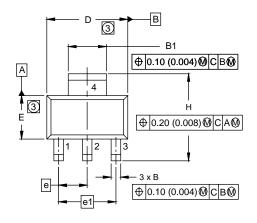


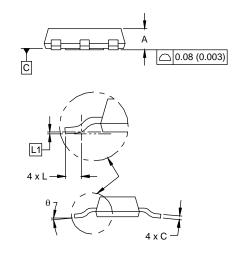
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





### SOT-223 (HIGH VOLTAGE)





|      | MILLI     | METERS | INCHES     |       |  |
|------|-----------|--------|------------|-------|--|
| DIM. | MIN.      | MAX.   | MIN.       | MAX.  |  |
| А    | 1.55      | 1.80   | 0.061      | 0.071 |  |
| В    | 0.65      | 0.85   | 0.026      | 0.033 |  |
| B1   | 2.95      | 3.15   | 0.116      | 0.124 |  |
| С    | 0.25      | 0.35   | 0.010      | 0.014 |  |
| D    | 6.30      | 6.70   | 0.248      | 0.264 |  |
| E    | 3.30      | 3.70   | 0.130      | 0.146 |  |
| е    | 2.30 BSC  |        | 0.0905 BSC |       |  |
| e1   | 4.60 BSC  |        | 0.181 BSC  |       |  |
| Н    | 6.71      | 7.29   | 0.264      | 0.287 |  |
| L    | 0.91      | -      | 0.036      | -     |  |
| L1   | 0.061 BSC |        | 0.002      | 4 BSC |  |
| θ    | -         | 10'    | -          | 10'   |  |

#### Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.

2. Dimensions are shown in millimeters (inches).

3. Dimension do not include mold flash.

4. Outline conforms to JEDEC outline TO-261AA.



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